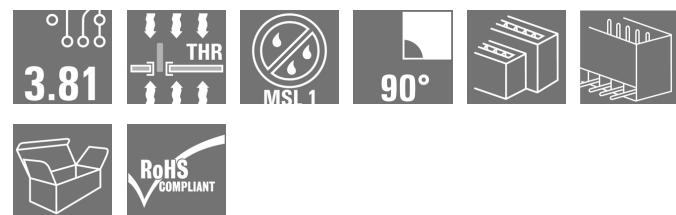


SCDN-THR 3.81/06/90G 3.2SN BK BX

Weidmüller Interface GmbH & Co. KG
 Klingenbergsstraße 26
 D-32758 Detmold
 Germany

www.weidmueller.com

Product image

Similar to illustration

Extra flat high-temperature-resistant two-tier SCDN-THR pin header for reflow soldering.

- Two compact interfaces are used with the flat BCF 3.81 (PUSH IN) socket block.
- Available as 90° (recumbent).
- Connections on a single level, allowing access that is flush over the front board.
- Space for labelling and coding
- Packed in cardboard box.

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of standard connectors and offer space for labelling and coding.

General ordering data

| | |
|--------------|---|
| Version | PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.81 mm, Number of poles: 6, 90°, Solder pin length (l): 3.2 mm, tinned, black, Box |
| Order No. | 1038960000 |
| Type | SCDN-THR 3.81/06/90G 3.2SN BK BX |
| GTIN (EAN) | 4032248772308 |
| Qty. | 50 pc(s). |
| Product data | IEC: 320 V / 17.5 A UL: 300 V / 11 A |
| Packaging | Box |

Creation date September 15, 2022 10:25:55 PM CEST

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Technical data

Dimensions and weights

| | | | |
|--------------------------|------------|-----------------|------------|
| Depth | 13.3 mm | Depth (inches) | 0.524 inch |
| Height | 18.4 mm | Height (inches) | 0.724 inch |
| Height of lowest version | 15.2 mm | Width | 12.82 mm |
| Width (inches) | 0.505 inch | Net weight | 3.08 g |

System specifications

| | | | |
|--|-------------------------------------|---|------------------|
| Product family | OMNIMATE Signal - series BC/SC 3.81 | Type of connection | Board connection |
| Mounting onto the PCB | THT/THR solder connection | Pitch in mm (P) | 3.81 mm |
| Pitch in inches (P) | 0.15 inch | Outgoing elbow | 90° |
| Number of poles | 6 | Number of solder pins per pole | 1 |
| Solder pin length (l) | 3.2 mm | Solder pin length tolerance | +0,02 / -0,02 mm |
| Solder pin dimensions | d = 1.0 mm, Octagonal | Solder pin dimensions = d tolerance | 0 / -0,03 mm |
| Solder eyelet hole diameter (D) | 1.3 mm | Solder eyelet hole diameter tolerance (D)+ 0,1 mm | |
| Outside diameter of solder pad | 2.1 mm | Template aperture diameter | 1.9 mm |
| L1 in mm | 7.62 mm | L1 in inches | 0.3 inch |
| Number of rows | 2 | Pin series quantity | 2 |
| Touch-safe protection acc. to DIN VDE 57 106 | Safe from finger touch | Touch-safe protection acc. to DIN VDE 0470 | IP 20 |
| Volume resistance | ≤5 mΩ | Can be coded | Yes |

Material data

| | | | |
|---------------------------------------|----------|---------------------------------------|--------------|
| Insulating material | LCP GF | Colour | black |
| Colour chart (similar) | RAL 9011 | Insulating material group | IIIa |
| Comparative Tracking Index (CTI) | ≥ 175 | Moisture Level (MSL) | 1 |
| UL 94 flammability rating | V-0 | Contact material | Copper alloy |
| Contact surface | tinned | Storage temperature, min. | -40 °C |
| Storage temperature, max. | 70 °C | Operating temperature, min. | -50 °C |
| Operating temperature, max. | 120 °C | Temperature range, installation, min. | -25 °C |
| Temperature range, installation, max. | 120 °C | | |

Rated data acc. to IEC

| | | | |
|---|------------------------|---|-------------------|
| tested acc. to standard | IEC 60664-1, IEC 61984 | Rated current, min. number of poles (Tu=20°C) | 17.5 A |
| Rated current, max. number of poles (Tu=20°C) | 13.2 A | Rated current, min. number of poles (Tu=40°C) | 17 A |
| Rated current, max. number of poles (Tu=40°C) | 12.2 A | Rated voltage for surge voltage class / pollution degree II/2 | 320 V |
| Rated voltage for surge voltage class / pollution degree III/2 | 160 V | Rated voltage for surge voltage class / pollution degree III/3 | 160 V |
| Rated impulse voltage for surge voltage class/ pollution degree II/2 | 2.5 kV | Rated impulse voltage for surge voltage class/ pollution degree III/2 | 2.5 kV |
| Rated impulse voltage for surge voltage class/ contamination degree III/3 | 2.5 kV | Short-time withstand current resistance | 3 x 1 s with 76 A |

Rated data acc. to CSA

| | | | |
|-----------------------------------|-------|-----------------------------------|-------|
| Rated voltage (Use group B / CSA) | 300 V | Rated voltage (Use group D / CSA) | 300 V |
| Rated current (Use group B / CSA) | 11 A | Rated current (Use group D / CSA) | 11 A |

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Technical data**Packing**

| | | | |
|-----------|--------|------------|--------|
| Packaging | Box | VPE length | 245 mm |
| VPE width | 130 mm | VPE height | 28 mm |

Classifications

| | | | |
|-------------|-------------|-------------|-------------|
| ETIM 6.0 | EC002637 | ETIM 7.0 | EC002637 |
| ETIM 8.0 | EC002637 | ECLASS 9.0 | 27-44-04-02 |
| ECLASS 9.1 | 27-44-04-02 | ECLASS 10.0 | 27-44-04-02 |
| ECLASS 11.0 | 27-46-02-01 | ECLASS 12.0 | 27-46-02-01 |

Important note

| | |
|----------------|--|
| IPC conformity | Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request. |
| Notes | <ul style="list-style-type: none"> Rated current related to rated cross-section & min. No. of poles. Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. P on drawing = pitch Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months |

Approvals

Approvals



| | |
|------|---------|
| ROHS | Conform |
|------|---------|

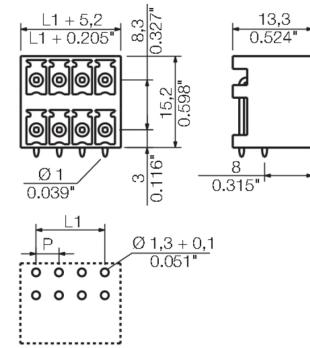
Downloads

| | |
|---|--|
| Approval/Certificate/Document of Conformity | Declaration of the Manufacturer |
| Engineering Data | CAD data – STEP |
| Catalogues | Catalogues in PDF-format |
| Brochures | FL DRIVES EN MB DEVICE MANUF. EN FL DRIVES DE FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL_INVERTER EN FL_BASE_STATION_EN FL_ELEVATOR_EN FL_POWER_SUPPLY_EN FL_72H_SAMPLE_SER_EN PO_OMNIMATE_EN PO_OMNIMATE_EN |
| White paper surface mount technology | Download Whitepaper |

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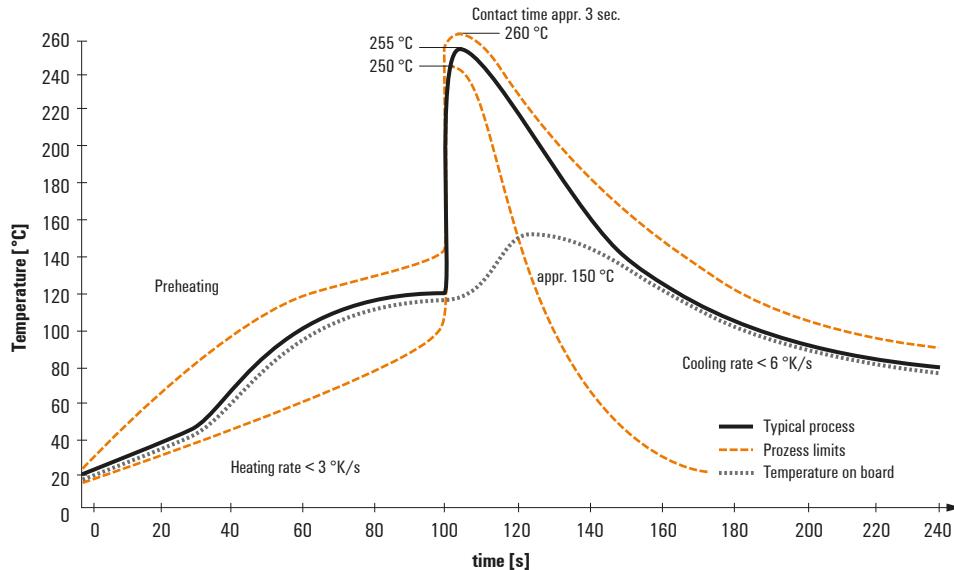
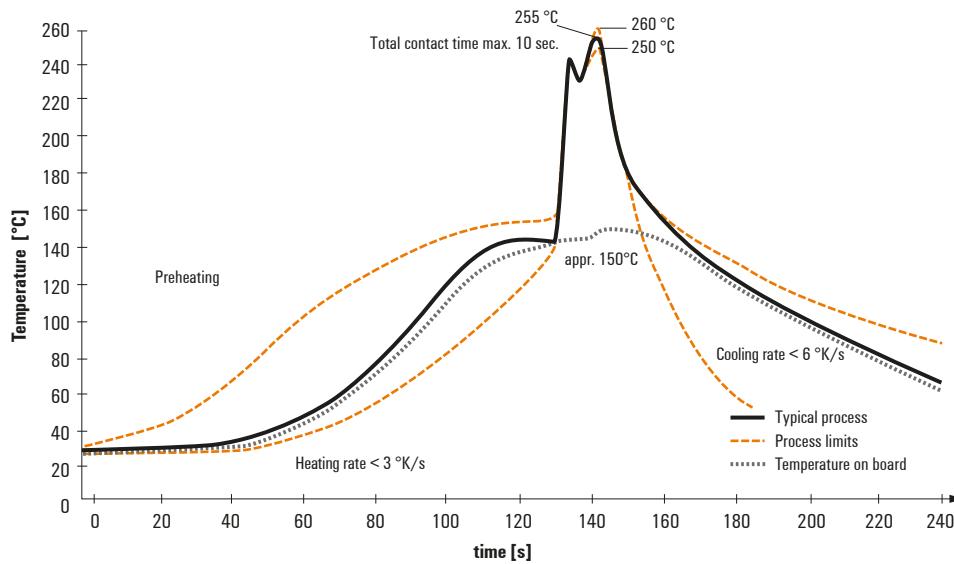
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Drawings**Dimensional drawing**

Recommended wave soldering profiles

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Single Wave:**Double Wave:****Wave soldering profiles**

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

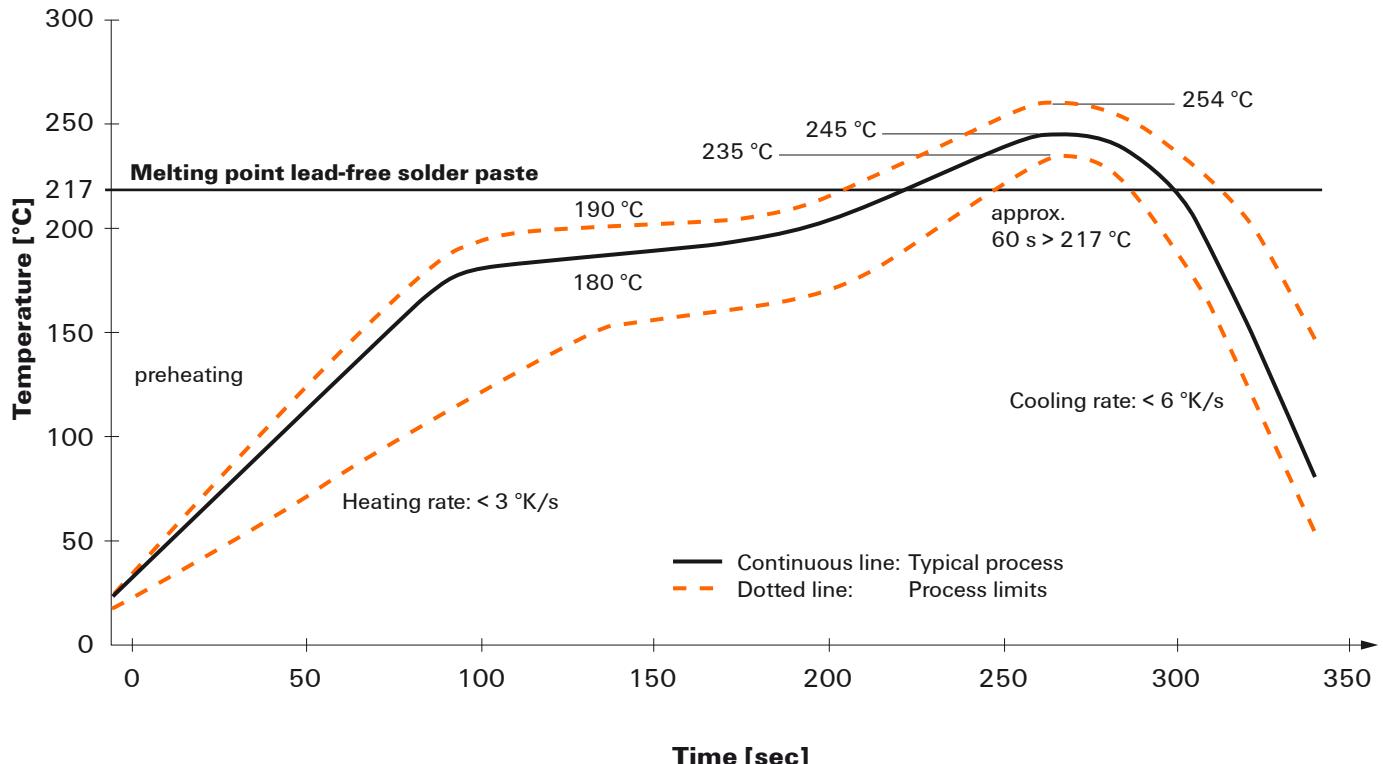
When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.